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Yoneyama et al.

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(54) **SEMICONDUCTOR DEVICE**

(56) **References Cited**

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(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
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361/679.01, 713, 728, 736, 760, 761,
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438/15, 25, 26, 51, 55, 63, 64, 106
CPC . H01L 21/00; H01L 2224/42; H01L 2021/00;
H01L 2021/02; H01L 2021/04; H01L
21/4814; H01L 21/4846; H01L 21/4871;
H01L 21/67144; H01L 23/12; H01L 23/13;
H01L 23/14; H01L 23/147; H01L 2924/171;
H01L 2924/1711; H01L 2924/1715; H01L
2924/17151; H01L 2924/181; H01L
2924/1811; H01L 2924/1815; H01L
2924/19042; H01L 2924/1905; H01L
2224/08054; H01L 23/58; H05B 41/14;
H02B 6/4201; G02B 6/4256; G02B 6/4257;
G02B 6/4261; G02B 6/4262; G02B 6/428;
G02B 6/4281; H05K 1/14; H05K 1/141;
H05K 1/142; H05K 1/144; H05K 1/18;
H05K 1/181; H05K 1/182; H05K 1/026

See application file for complete search history.

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(57) **CLAIM**

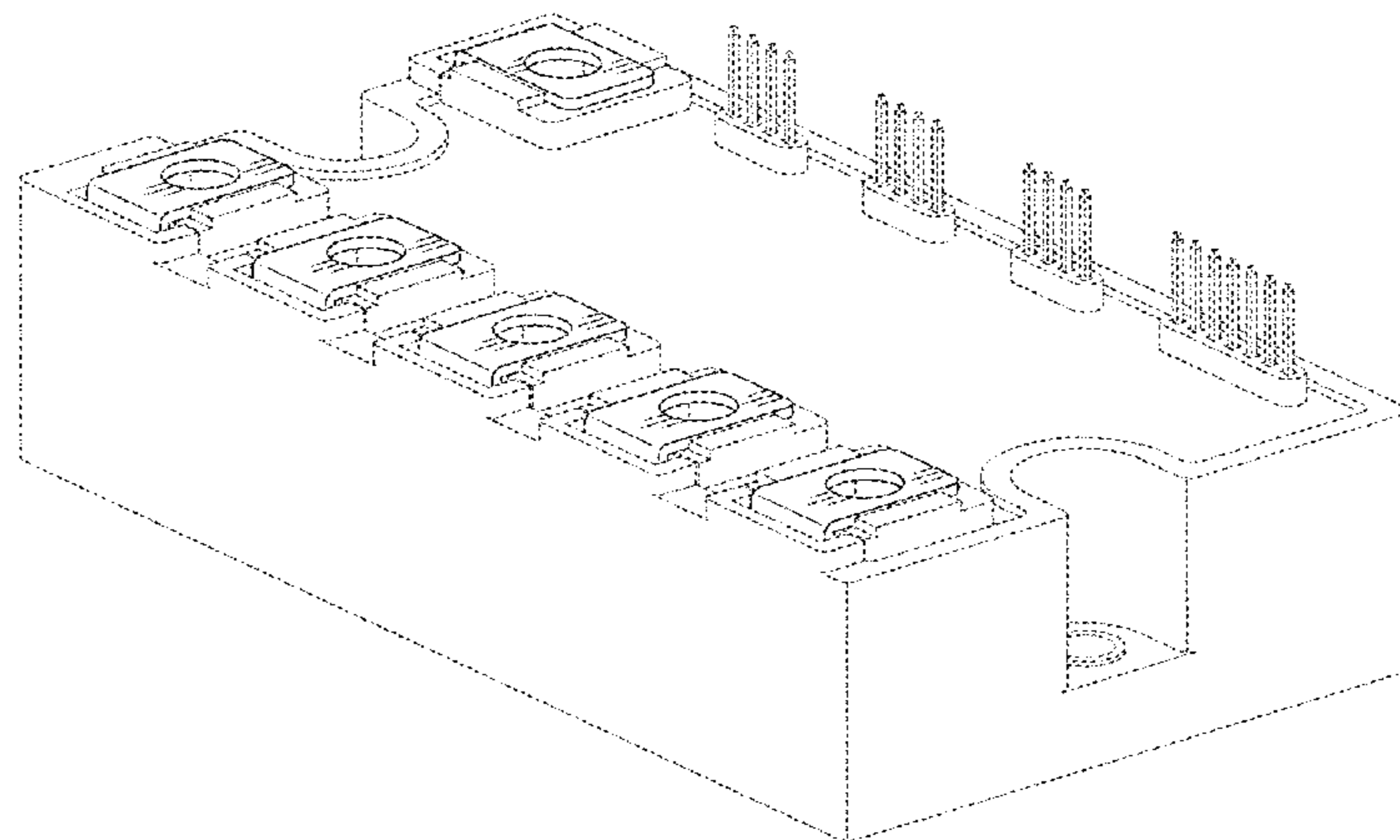
The ornamental design for a semiconductor device, as shown and described.

DESCRIPTION

FIG. 1 is a front, top and right side perspective view of a semiconductor device, showing our new design;
 FIG. 2 is a front view thereof;
 FIG. 3 is a rear view thereof;
 FIG. 4 is a left side view thereof;
 FIG. 5 is a right side view thereof;
 FIG. 6 is a top view thereof; and,
 FIG. 7 is a bottom view thereof.

The broken lines shown in the drawings represent portions of the semiconductor device, that form no part of the claimed design.

1 Claim, 7 Drawing Sheets



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Fig. 1

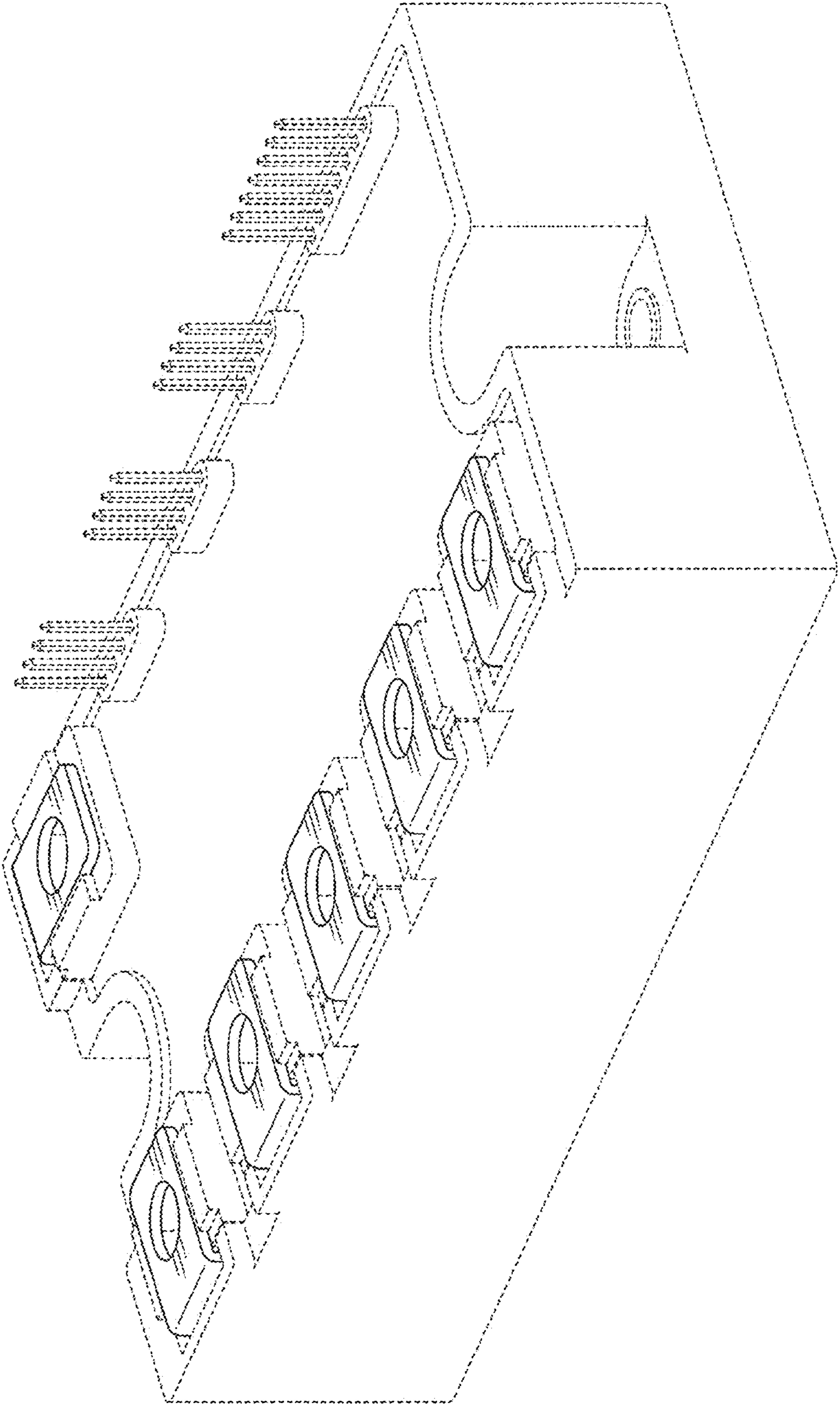


Fig. 2

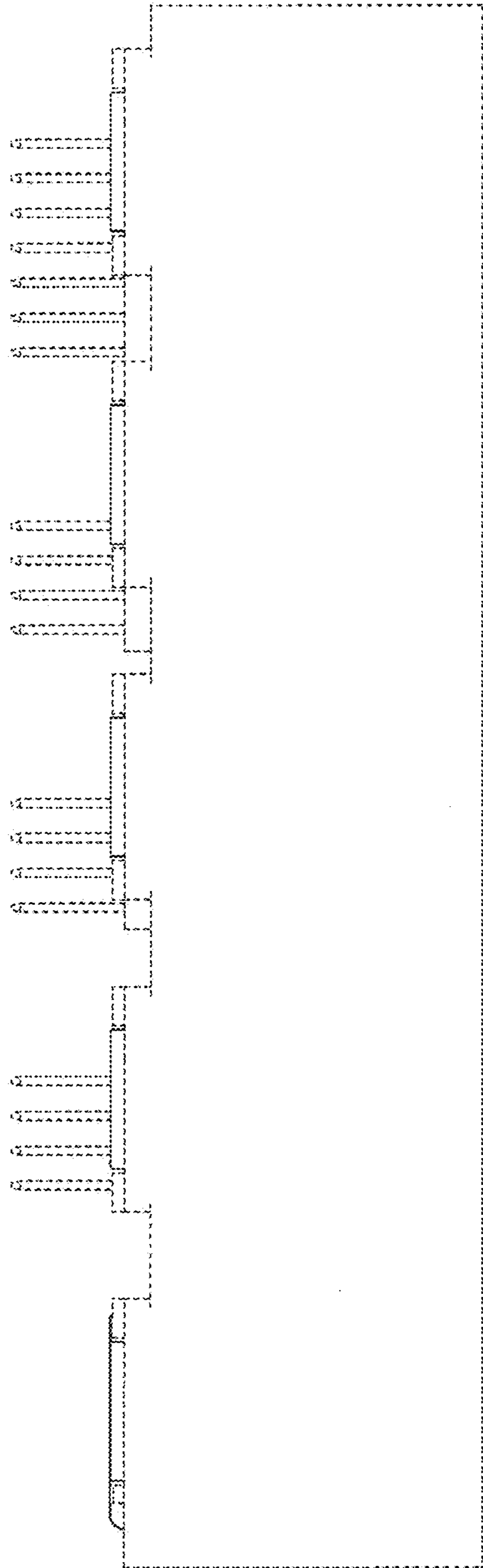


Fig. 3

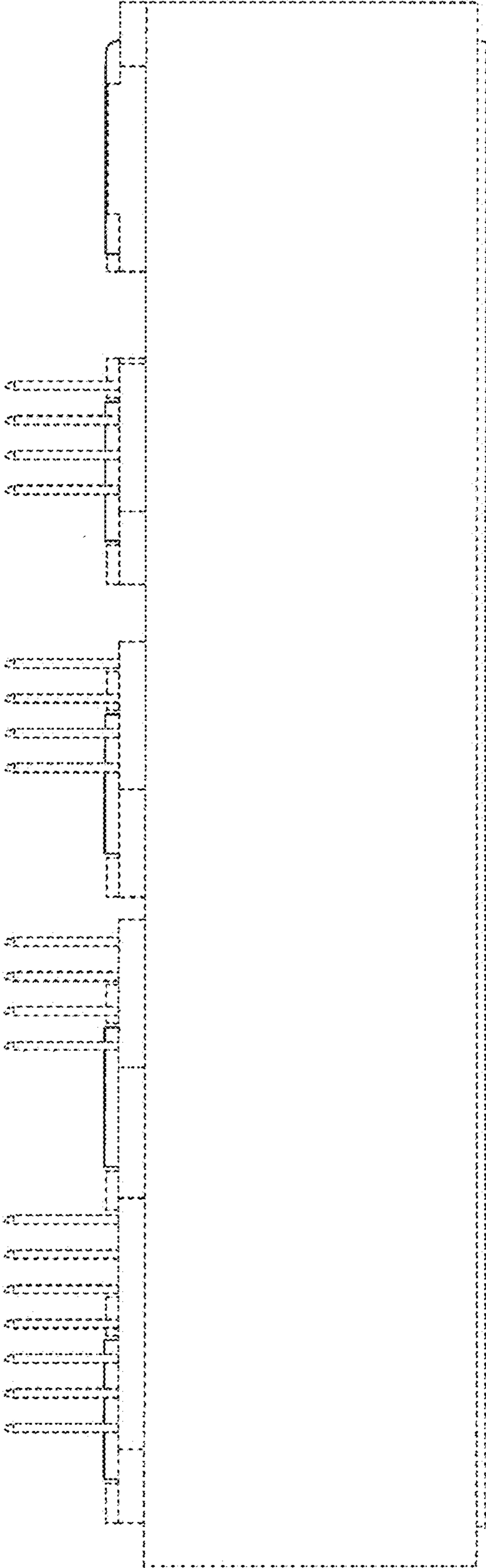


Fig. 4

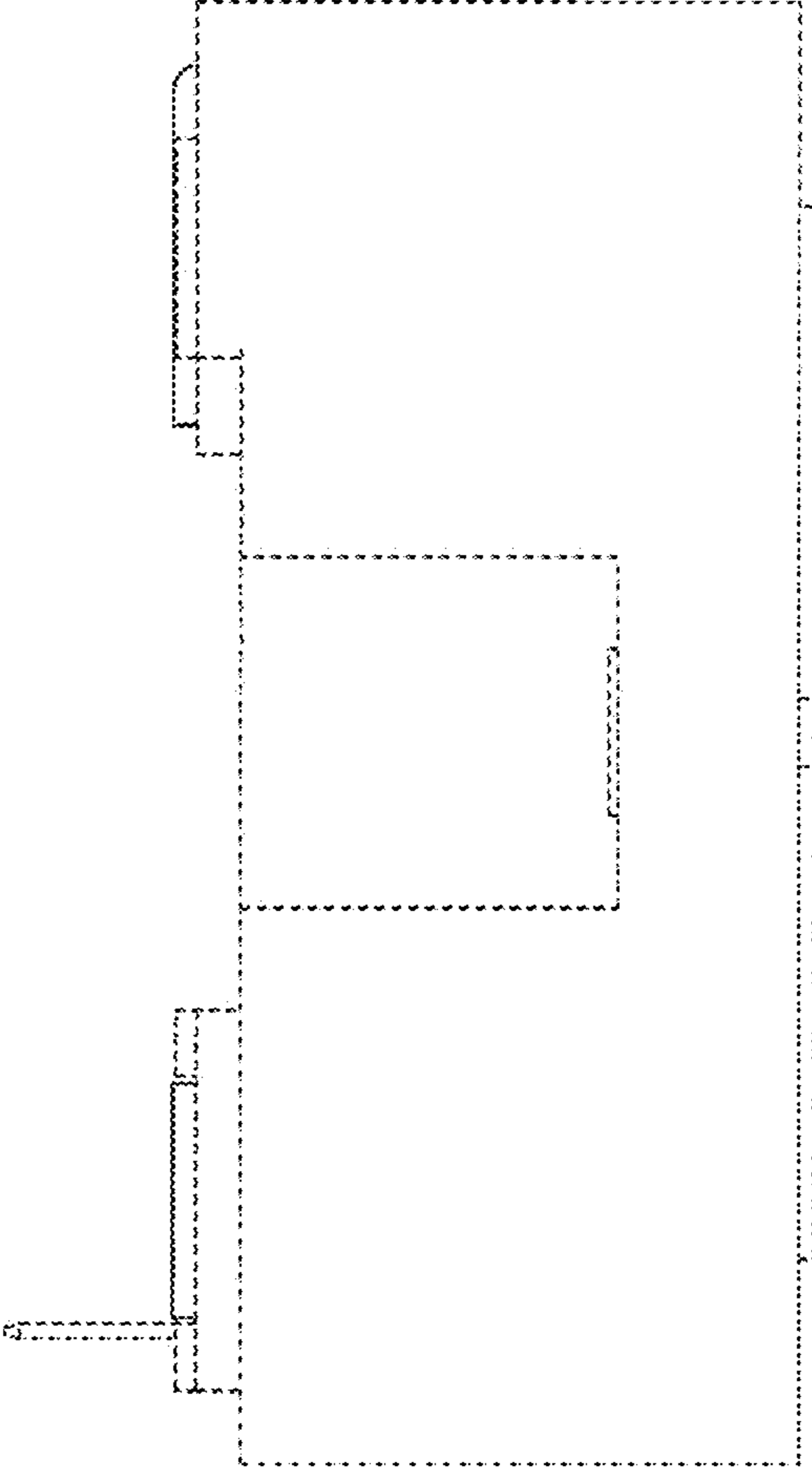


Fig. 5

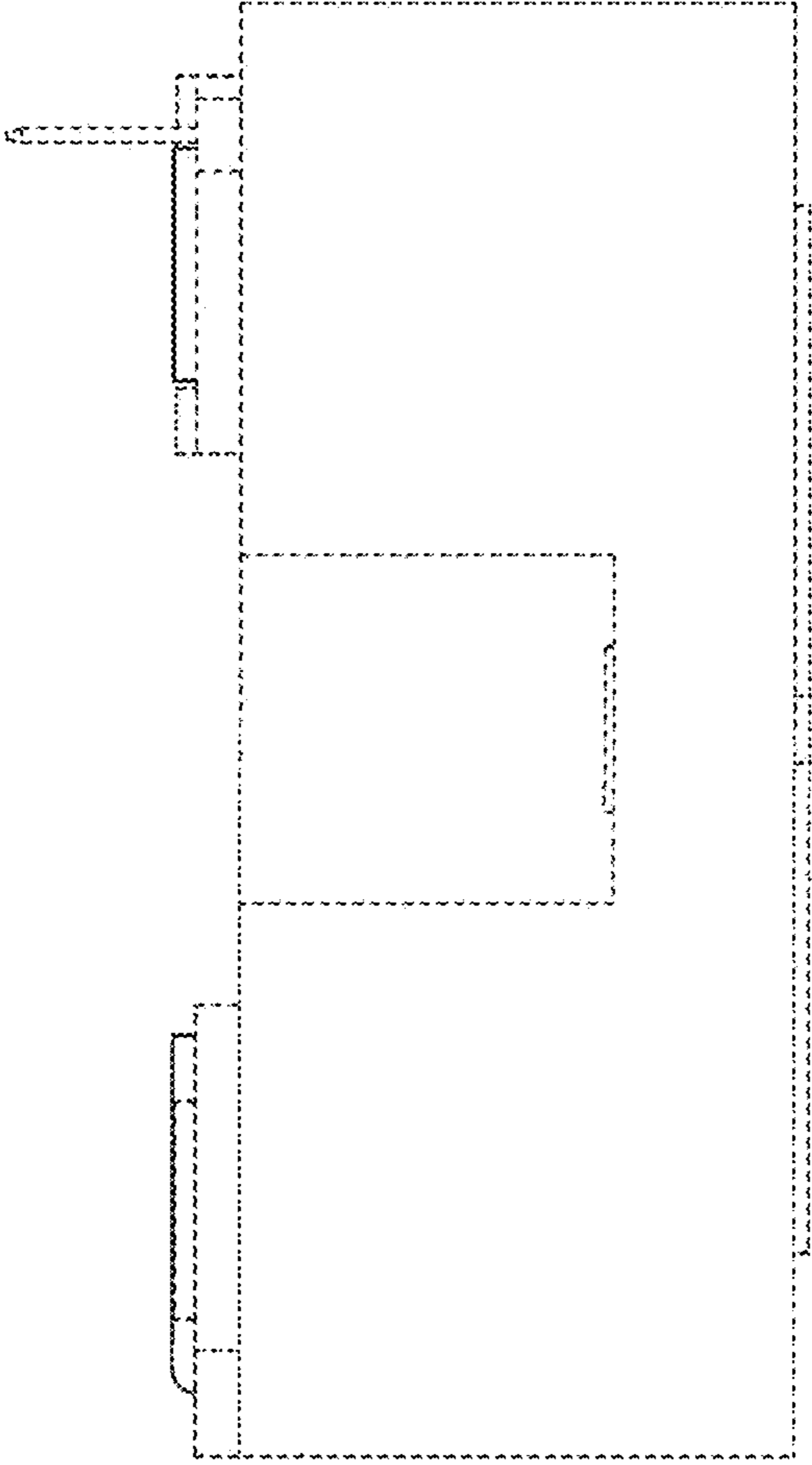


Fig. 6

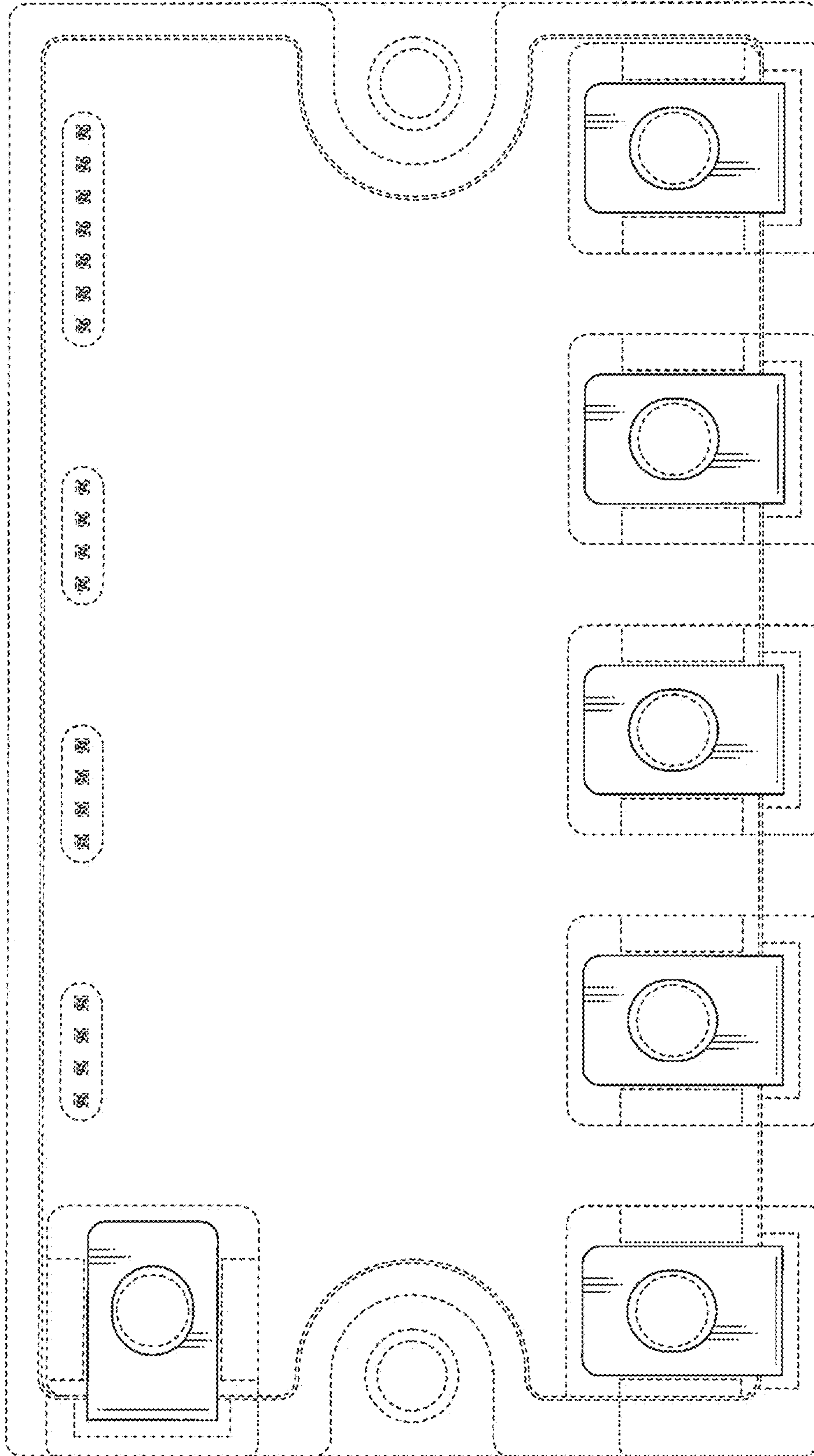


Fig. 7

